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41st Semiconductor Thermal Measurement, Modeling and Management Symposium

March 10-14, 2025 at the DoubleTree by Hilton, San Jose, CA USA

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Symposium highlights

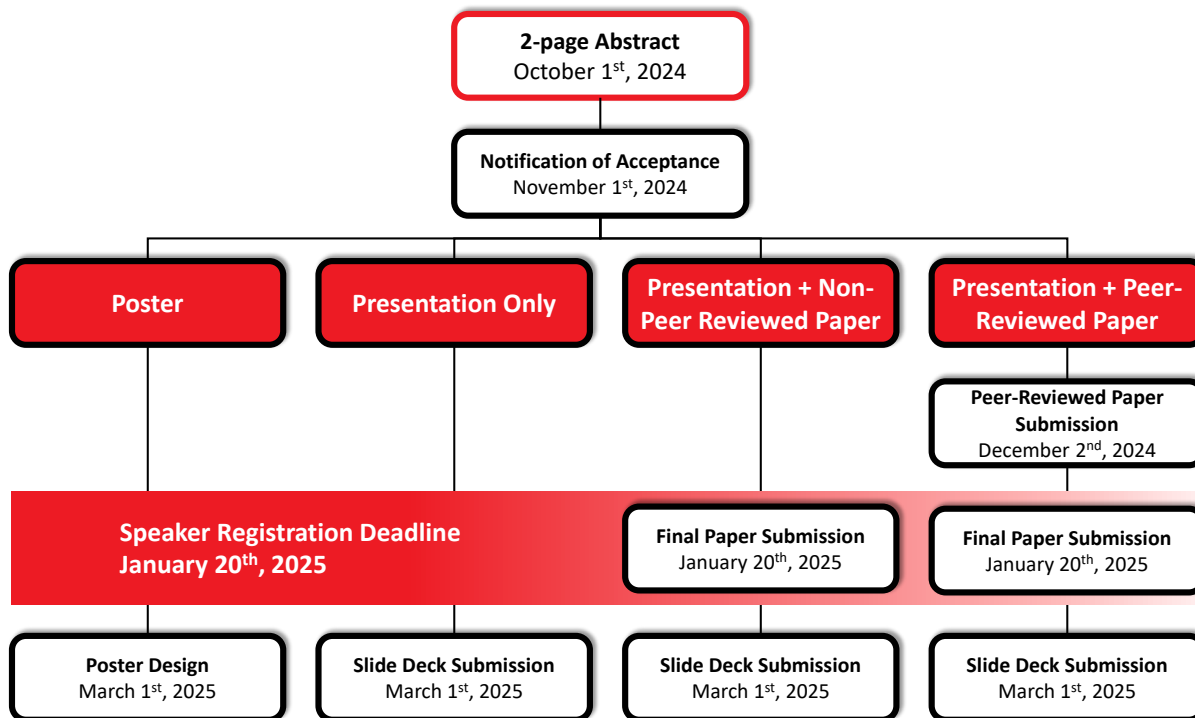
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Vendor Workshops

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Tutorials
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Four options for participating in the technical program



Awards: All papers are eligible for the Best Paper Award. Presentations made by students are eligible for Best Student Presentation Awards. Other presentation-only submissions are not eligible for awards.

For further information please contact the Program Chair
Navid Kazem, CEO, Arieca Inc., E-mail: navid@arieca.com
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** All authors qualify for reduced symposium rates **